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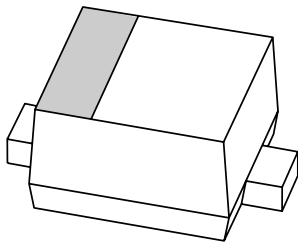
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DATA SHEET



PMEG2005EB

Low V_F MEGA Schottky barrier diode

Product data sheet
Supersedes data of 2003 Feb 20

2003 Apr 04

Low V_F MEGA Schottky barrier diode

PMEG2005EB

FEATURES

- Forward current: 0.5 A
- Reverse voltage: 20 V
- Very low forward voltage
- Guard ring protected
- Ultra small SMD package.

APPLICATIONS

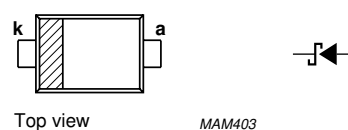
- Ultra high-speed switching
- Voltage clamping
- Protection circuits
- Low current rectification
- Low power consumption applications (e.g. handheld devices).

DESCRIPTION

Planar Maximum Efficiency General Application (MEGA) Schottky barrier diode, encapsulated in a SOD523 (SC-79) ultra small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



Marking code: L5.

The marking bar indicates the cathode.

Fig.1 Simplified outline (SOD523; SC-79) and symbol.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		–	20	V
I_F	continuous forward current		–	500	mA
I_{FRM}	repetitive peak forward current	$t_p = 1 \text{ ms}$; $\delta \leq 0.25$	–	3.5	A
I_{FSM}	non-repetitive peak forward current	$t = 8 \text{ ms square wave}$	–	6	A
T_{stg}	storage temperature		–65	+150	°C
T_j	junction temperature		–	125	°C
T_{amb}	operating ambient temperature		–65	+125	°C

Low V_F MEGA Schottky barrier diode

PMEG2005EB

ELECTRICAL CHARACTERISTICS

$T_{amb} = 25\text{ }^{\circ}\text{C}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V_F	continuous forward voltage	see Fig.2			
		$I_F = 0.1\text{ mA}$	120	180	mV
		$I_F = 1\text{ mA}$	180	240	mV
		$I_F = 10\text{ mA}$	245	290	mV
		$I_F = 100\text{ mA}$	320	380	mV
		$I_F = 500\text{ mA}$	430	480	mV
I_R	continuous reverse current	$V_R = 10\text{ V}$; see Fig.3; note 1	7	30	μA
C_d	diode capacitance	$V_R = 1\text{ V}$; $f = 1\text{ MHz}$; see Fig.4	24	30	pF

Note

1. Pulsed test: $t_p = 300\text{ }\mu\text{s}$; $\delta = 0.02$.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\text{ j-a}}$	thermal resistance from junction to ambient	note 1	400	K/W

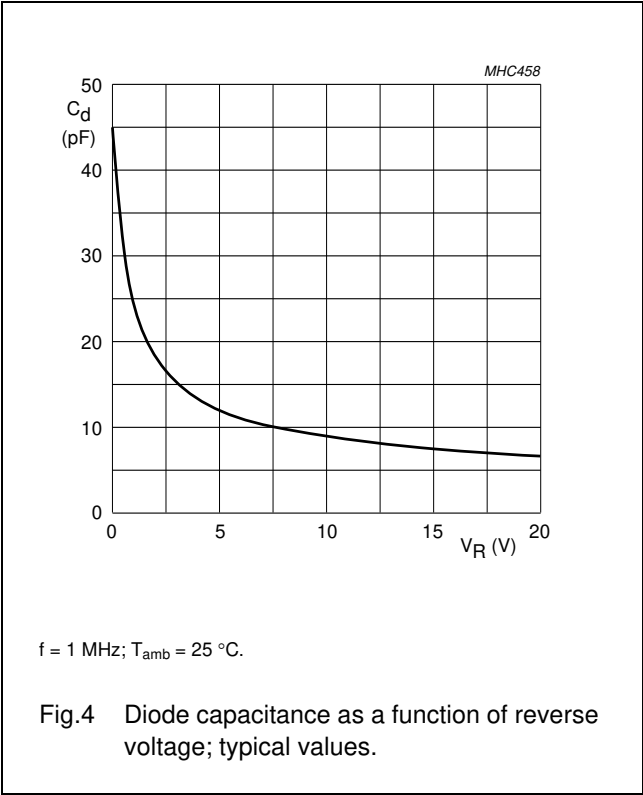
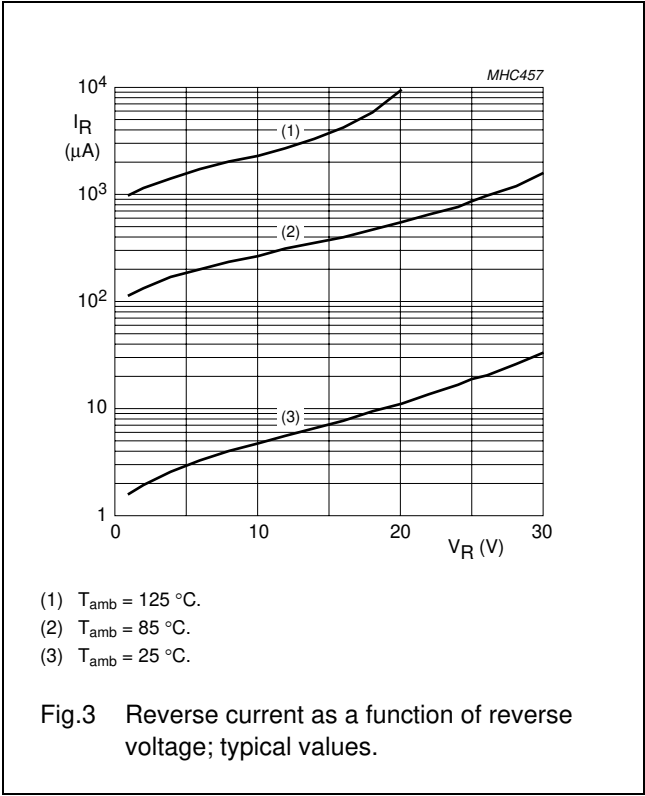
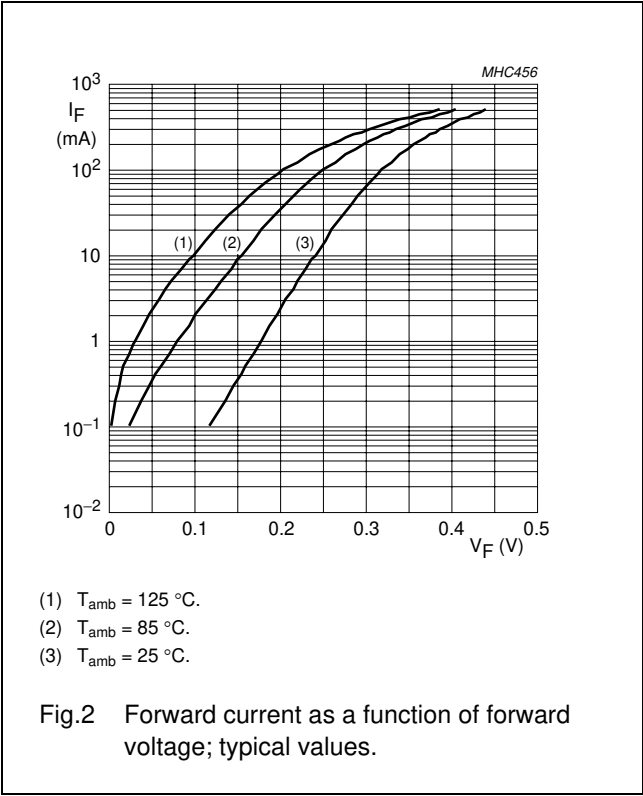
Note

1. Refer to SOD523 (SC-79) standard mounting conditions.

Low V_F MEGA Schottky barrier diode

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GRAPHICAL DATA



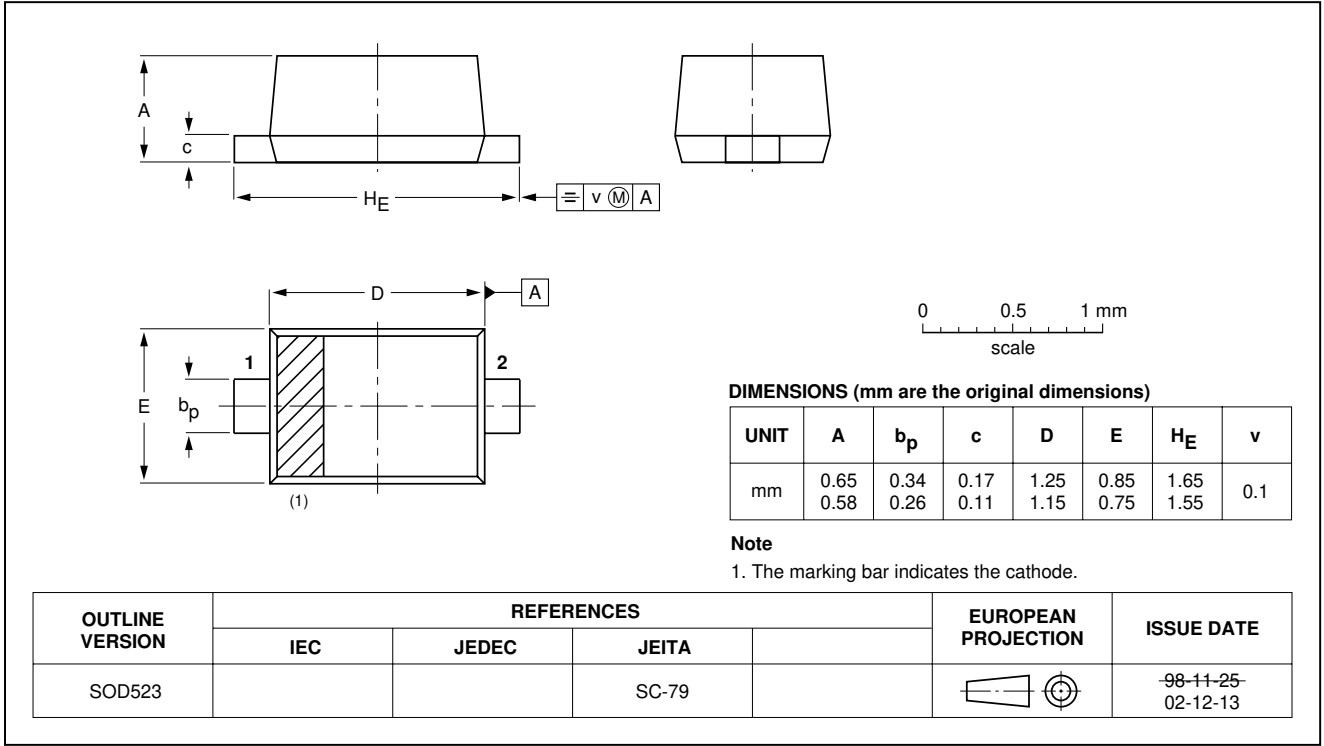
Low V_F MEGA Schottky barrier diode

PMEG2005EB

PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SOD523



Low V_F MEGA Schottky barrier diode

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DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

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Contact information

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Printed in The Netherlands

613514/02/pp7

Date of release: 2003 Apr 04

Document order number: 9397 750 11354

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